

MECHANICAL CASE OUTLINE

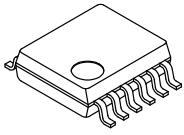
PACKAGE DIMENSIONS

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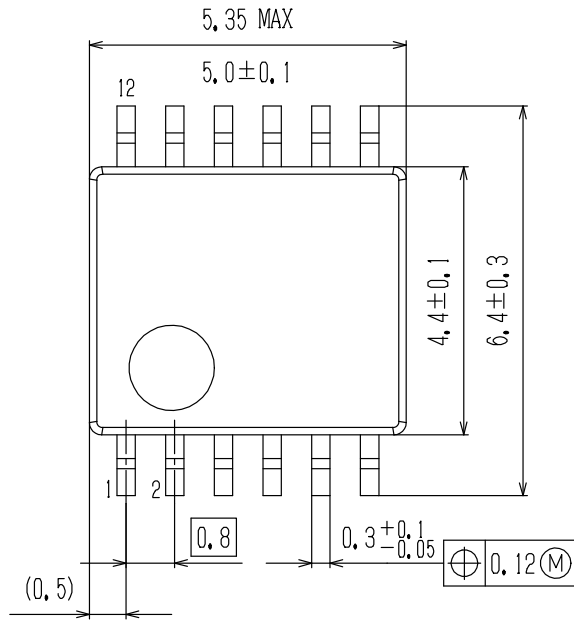


SOIC12 W / MFP12S (225 mil)
CASE 751BY
ISSUE O

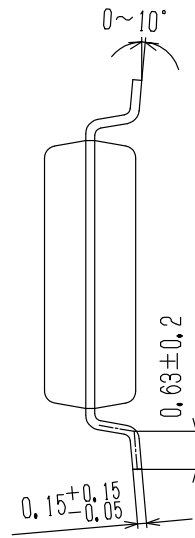
DATE 29 FEB 2012



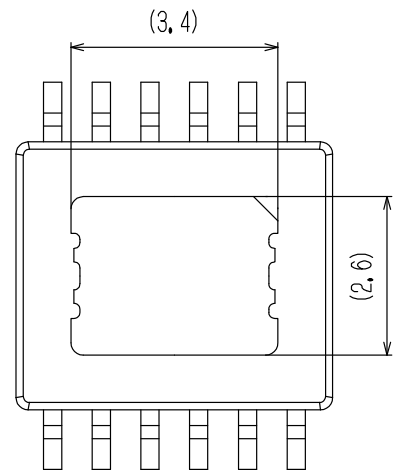
TOP VIEW



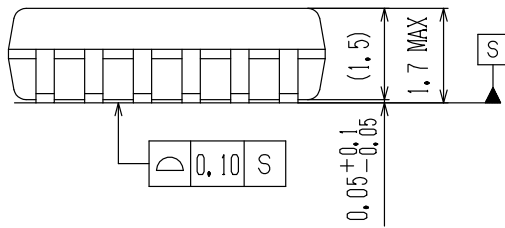
SIDE VIEW



BOTTOM VIEW



SIDE VIEW



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